

**PART INFORMATION**

Mfg Item Number	MCIMX6V7DVN10AB
Mfg Item Name	MAPBGA 432 13*13 P0.5

**SUPPLIER**

Company Name	Freescale Semiconductor Inc
Company Unique ID	14-141-7928
Response Date	2018-02-10
Response Document ID	00CHA1.7
Contact Name	Freescale Semiconductor Inc
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**DECLARATION**

EU RoHS	Yes
Pb Free	Yes
HalogenFree	Yes
Plating Indicator	e1
EU RoHS Exemption(s)	

**MANUFACTURING**

Mfg Item Number	MCIMX6V7DVN10AB
Mfg Item Name	MAPBGA 432 13*13 P0.5
Version	ALL
Weight	0.587900
UoM	g
Unit Volume	EACH
J-STD-020 MSL Rating	3
Peak Processing Temperature	260 C
Max Time at Peak Temperature	40 seconds
Number of Processing Cycles	3

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.
RoHS Declaration	1 - Item(s) do not contain RoHS restricted substances per the definition above
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemption List Version	2012/51/EU
List of Freescale Accepted Exemptions	<p>6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight</p> <p>6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight</p> <p>6(c) : Copper alloy containing up to 4% lead by weight</p> <p>7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)</p> <p>7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications</p> <p>7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound</p> <p>7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher</p> <p>7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC</p> <p>7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors</p> <p>15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages</p>

MATERIAL COMPOSITION

Homogeneous Material	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%	ARTICLEPPM	ARTICLE%
Non-Conductive Epoxy/Adhesive	0.0015						g				
Non-Conductive Epoxy/Adhesive		Plastics/polymers	Proprietary Material-Other Epoxy resins	-		0.0001125	g	75000	7.5	191	0.0191
Non-Conductive Epoxy/Adhesive		Plastics/polymers	Crosslinked acrylate polymer	25767-43-5		0.0003	g	200000	20	510	0.051
Non-Conductive Epoxy/Adhesive		Plastics/polymers	Other polymers	-		0.0001125	g	75000	7.5	191	0.0191
Non-Conductive Epoxy/Adhesive		Plastics/polymers	Proprietary Material-Other polymers	-		0.0003	g	200000	20	510	0.051
Non-Conductive Epoxy/Adhesive		Glass	Silica, vitreous	60676-86-0		0.000675	g	450000	45	1148	0.1148
Solder Balls - Lead Free	0.2203						g				
Solder Balls - Lead Free		Metals	Aluminum, metal	7429-90-5		0.0000011	g	5	0.0005	1	0.0001
Solder Balls - Lead Free		Antimony/Antimony Compounds	Antimony (metallic)	7440-36-0		0.00002203	g	100	0.01	37	0.0037
Solder Balls - Lead Free		Arsenic/Arsenic Compounds	Arsenic	7440-38-2		0.00002203	g	100	0.01	37	0.0037
Solder Balls - Lead Free		Bismuth/Bismuth Compounds	Bismuth	7440-69-9		0.00003305	g	150	0.015	56	0.0056
Solder Balls - Lead Free		Cadmium/Cadmium Compounds	Cadmium	7440-43-9		0.0000022	g	10	0.001	3	0.0003
Solder Balls - Lead Free		Metals	Copper, metal	7440-50-8		0.00110062	g	4996	0.4996	1872	0.1872
Solder Balls - Lead Free		Metals	Gold, metal	7440-57-5		0.00001102	g	50	0.005	18	0.0018
Solder Balls - Lead Free		Metals	Iron, metal	7439-89-6		0.00002203	g	100	0.01	37	0.0037
Solder Balls - Lead Free		Lead/Lead Compounds	Lead	7439-92-1		0.00006609	g	300	0.03	112	0.0112
Solder Balls - Lead Free		Nickel (external applications only)	Nickel	7440-02-0		0.00000551	g	25	0.0025	9	0.0009
Solder Balls - Lead Free		Metals	Silver, metal	7440-22-4		0.00220124	g	9992	0.9992	3744	0.3744
Solder Balls - Lead Free		Metals	Tin, metal	7440-31-5		0.21681198	g	984167	98.4167	368809	36.8809
Solder Balls - Lead Free		Metals	Zinc, metal	7440-66-6		0.0000011	g	5	0.0005	1	0.0001
Bonding Wire, PdCu	0.0037						g				
Bonding Wire, PdCu		Metals	Copper, metal	7440-50-8		0.00362968	g	980994	98.0994	6173	0.6173
Bonding Wire, PdCu		Metals	Gold, metal	7440-57-5		0.0000037	g	1000	0.1	6	0.0006
Bonding Wire, PdCu		Metals	Palladium, metal	7440-05-3		0.00006662	g	18006	1.8006	113	0.0113
Die Encapsulant, Halogen-free	0.2362						g				
Die Encapsulant, Halogen-free		Metals	Aluminum, metal	7429-90-5		0.005905	g	25000	2.5	10044	1.0044
Die Encapsulant, Halogen-free		Metals	Magnesium, metal	7439-96-4		0.002362	g	10000	1	4017	0.4017
Die Encapsulant, Halogen-free		Solvents, additives, and other materials	Other organic phosphorous compounds	-		0.002362	g	10000	1	4017	0.4017
Die Encapsulant, Halogen-free		Solvents, additives, and other materials	Silicone modified epoxy resin	218163-11-2		0.027163	g	115000	11.5	46203	4.6203
Die Encapsulant, Halogen-free		Solvents, additives, and other materials	Other organic Silicon Compounds	-		0.002362	g	10000	1	4017	0.4017
Die Encapsulant, Halogen-free		Glass	Silicon dioxide	7631-86-9		0.1896	g	800000	80	32145	32.145
Die Encapsulant, Halogen-free		Plastics/polymers	Proprietary Material-Other acrylic/epoxy resin mixture	-		0.001181	g	5000	0.5	2008	0.2008
Die Encapsulant, Halogen-free		Glass	Silica, amorphous synthetic	112926-00-8		0.005905	g	25000	2.5	10044	1.0044
Organic Substrate	0.112						g				
Organic Substrate		Metals	Barium sulfate	7727-43-7		0.00750781	g	67034	6.7034	12770	1.277
Organic Substrate		Metals	Copper, metal	7440-50-8		0.05658811	g	505251	50.5251	96254	9.6254
Organic Substrate		Metals	Gold, metal	7440-57-5		0.0036168	g	30015	3.0015	5718	0.5718
Organic Substrate		Metals	Talc	14807-96-6		0.000056	g	500	0.05	95	0.0095
Organic Substrate		Nickel (external applications only)	Nickel	7440-02-0		0.02465232	g	220110	22.011	41932	4.1932
Organic Substrate		Solvents, additives, and other materials	Silicone modified epoxy resin	218163-11-2		0.00571491	g	51026	5.1026	9720	0.972
Organic Substrate		Glass	Fibrous-glass-wool	65997-17-3		0.00571491	g	51026	5.1026	9720	0.972
Organic Substrate		Glass	Silica, vitreous	60676-86-0		0.00840426	g	75038	7.5038	14295	1.4295
Silicon Semiconductor Die	0.0142						g				
Silicon Semiconductor Die		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%)	-		0.000284	g	20000	2	483	0.0483
Silicon Semiconductor Die		Glass	Silicon, doped	-		0.013916	g	980000	98	23670	2.367

## LINKS

MCD LINK	
NXP website	<a href="http://www.nxp.com">http://www.nxp.com</a>
GENERAL ENVIRONMENTAL COMPLIANCE LINKS	
RoHS signed letter	<a href="http://www.nxp.com/files/corporate/doc/support_info/NXP-ROHS-DECLARATION.pdf">http://www.nxp.com/files/corporate/doc/support_info/NXP-ROHS-DECLARATION.pdf</a>
China RoHS	<a href="http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/china-rohs:ENV_CHINA_ROHS_STRATEGY">http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/china-rohs:ENV_CHINA_ROHS_STRATEGY</a>
REACH signed letter	<a href="http://www.nxp.com/files/corporate/doc/support_info/NXP-REACH-STATEMENT.pdf">http://www.nxp.com/files/corporate/doc/support_info/NXP-REACH-STATEMENT.pdf</a>
ELV signed letter	<a href="http://www.nxp.com/files/corporate/doc/support_info/NXP-ELV-STATEMENT.pdf">http://www.nxp.com/files/corporate/doc/support_info/NXP-ELV-STATEMENT.pdf</a>
Conflict Minerals statement	<a href="http://www.nxp.com/files/corporate/doc/support_info/NXP-STATEMENT-CONFLICT-MINERALS.pdf">http://www.nxp.com/files/corporate/doc/support_info/NXP-STATEMENT-CONFLICT-MINERALS.pdf</a>
NXP ENVIRONMENTAL INFORMATION	
Environmental Compliance website	<a href="http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization:ABUENVPRFPRDX">http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization:ABUENVPRFPRDX</a>
FAQ	<a href="http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/eco-product-faqs:ENVIRON_FAQ">http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/eco-product-faqs:ENVIRON_FAQ</a>
Technical Service Request	<a href="http://www.nxp.com/support/sales-and-support:SUPPORTHOME">http://www.nxp.com/support/sales-and-support:SUPPORTHOME</a>
LINKS TO BLANK IPC1752 FORMS	
Blank IPC1752 v1.1 Form	<a href="http://www.NXP.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf">http://www.NXP.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf</a>

IPC1752 XML LINKS

[http://www.freescale.com/mcdfs/MCIMX6V7DVN10AB\\_IPC1752\\_v11.xml](http://www.freescale.com/mcdfs/MCIMX6V7DVN10AB_IPC1752_v11.xml)

[http://www.freescale.com/mcdfs/MCIMX6V7DVN10AB\\_IPC1752A.xml](http://www.freescale.com/mcdfs/MCIMX6V7DVN10AB_IPC1752A.xml)